

**PART INFORMATION**

Mfg Item Number	MPC8343CZQAGDB
Mfg Item Name	PBGA 620 29*29*1.2P1.0

**SUPPLIER**

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2017-09-19
Response Document ID	5203K11038D034A1.39
Contact Name	Freescale Semiconductor Inc
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URL for Additional Information	www.freescale.com

**DECLARATION**

EU RoHS	No
Pb Free	No
HalogenFree	Yes
Plating Indicator	e0
EU RoHS Exemption(s)	

**MANUFACTURING**

Mfg Item Number	MPC8343CZQAGDB
Mfg Item Name	PBGA 620 29*29*1.2P1.0
Version	ALL
Weight	4.359000
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	3 - Item(s) does not contain RoHS restricted substances per the definition above except for lead in solders and selected exemptions, if any
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Epoxy Die Attach	0.0093						g				
Epoxy Die Attach		Solvents, additives, and other materials	1,3,5-Triazine-2,4-diamine, 6-[2-(2-methyl-1H-imidazol-1-yl)ethyl]	38668-46-1		0.0007859	g	8451	0.8451	18	0.0018
Epoxy Die Attach		Plastics/polymers	Phenolic Polymer Resin, Epikote 155	9003-36-5		0.00120508	g	129579	12.9579	276	0.0276
Epoxy Die Attach		Plastics/polymers	4,4'-Dihydroxydiphenyl	92-88-6		0.0007859	g	8451	0.8451	18	0.0018
Epoxy Die Attach		Metals	Silver, metal	7440-22-4		0.00793774	g	853519	85.3519	1821	0.1821
Solder Balls - Low Lead	0.5996						g				
Solder Balls - Low Lead		Lead/Lead Compounds	Lead	7439-92-1		0.215856	g	360000	36	48619	4.8619
Solder Balls - Low Lead		Metals	Silver, metal	7440-22-4		0.011982	g	20000	2	2751	0.2751
Solder Balls - Low Lead		Metals	Tin, metal	7440-31-5		0.371752	g	620000	62	85283	8.5283
Organic Substrate, Halogen-free	1.4314						g				
Organic Substrate, Halogen-free		Solvents, additives, and other materials	Other Aromatic hydrocarbon compounds	-		0.01109908	g	7754	0.7754	2546	0.2546
Organic Substrate, Halogen-free		Metals	Barium sulfate	7727-43-7		0.07932246	g	55416	5.5416	18197	1.8197
Organic Substrate, Halogen-free		Metals	Copper, metal	7440-50-8		0.0049426	g	352518	35.2518	115759	11.5759
Organic Substrate, Halogen-free		Metals	Gold, metal	7440-57-5		0.01989932	g	13902	1.3902	4665	0.4665
Organic Substrate, Halogen-free		Metals	Other nickel compounds	-		0.15386691	g	107494	10.7494	35298	3.5298
Organic Substrate, Halogen-free		Solvents, additives, and other materials	Other organic phosphorous compounds	-		0.18058696	g	126161	12.6161	41428	4.1428
Organic Substrate, Halogen-free		Plastics/polymers	Other polymers	-		0.10724908	g	74626	7.4626	24604	2.4604
Organic Substrate, Halogen-free		Glass	Other silica compounds	-		0.37476203	g	261829	26.1829	85978	8.5978
Non-Conductive Epoxy/Adhesive	0.0059						g				
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.000059	g	10000	1	13	0.0013
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Siloxanes and silicones, di-Me, vinyl group-terminated	68083-19-2		0.002655	g	450000	45	609	0.0609
Non-Conductive Epoxy/Adhesive		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.000059	g	10000	1	13	0.0013
Non-Conductive Epoxy/Adhesive		Glass	Silica, vitreous	60676-86-0		0.00118	g	200000	20	270	0.027
Non-Conductive Epoxy/Adhesive		Glass	Other silica compounds	-		0.00118	g	200000	20	270	0.027
Non-Conductive Epoxy/Adhesive		Glass	Dimethyl silicone polymer with silica	67762-90-7		0.000472	g	80000	8	108	0.0108
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Dimethyl methyl hydrogen siloxane	68037-59-2		0.000295	g	50000	5	67	0.0067
Heat Spreader	1.1178						g				
Heat Spreader		Metals	Copper, metal	7440-50-8		1.1178	g	1000000	100	256449	25.6449
Die Encapsulant, Halogen-free	1.1467						g				
Die Encapsulant, Halogen-free		Plastics/polymers	Other Epoxy resins	-		0.068802	g	60000	6	15783	1.5783
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.011467	g	10000	1	2630	0.263
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Other inorganic compounds	-		0.022934	g	20000	2	5261	0.5261
Die Encapsulant, Halogen-free		Plastics/polymers	Other phenolic resins	-		0.057335	g	50000	5	13153	1.3153
Die Encapsulant, Halogen-free		Glass	Silica, vitreous	60676-86-0		0.986162	g	860000	86	226235	22.6235
Bonding Wire, Copper	0.0183						g				
Bonding Wire, Copper		Metals	Copper, metal	7440-50-8		0.017751	g	970000	97	4072	0.4072
Bonding Wire, Copper		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.000549	g	30000	3	125	0.0125
Silicon Semiconductor Die	0.03						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.0006	g	20000	2	137	0.0137
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.0294	g	980000	98	6744	0.6744

## LINKS

MCD LINK	
NXP website	<a href="http://www.nxp.com">http://www.nxp.com</a>
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf</a>
China RoHS	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY</a>
REACH signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf</a>
ELV signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf</a>
Conflict Minerals statement	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf</a>
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX</a>
FAQ	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ</a>
Technical Service Request	<a href="http://www.nxp.com/support/sales-and-support:SUPPORTHOME">http://www.nxp.com/support/sales-and-support:SUPPORTHOME</a>
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	<a href="http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf">http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf</a>

IPC1752 XML LINKS

[http://www.freescale.com/mcdfs/MPC8343CZQAGDB\\_IPC1752\\_v11.xml](http://www.freescale.com/mcdfs/MPC8343CZQAGDB_IPC1752_v11.xml)

[http://www.freescale.com/mcdfs/MPC8343CZQAGDB\\_IPC1752A.xml](http://www.freescale.com/mcdfs/MPC8343CZQAGDB_IPC1752A.xml)